

DO NOT SCALE FROM THIS PRINT

DESIGNED & DIMENSIONED IN MILLIMETERS [INCHES]

PCIE-LP-XX-01-X-DV-A-XX-X-XX

No OF LANES
-01, -04, -08, -16

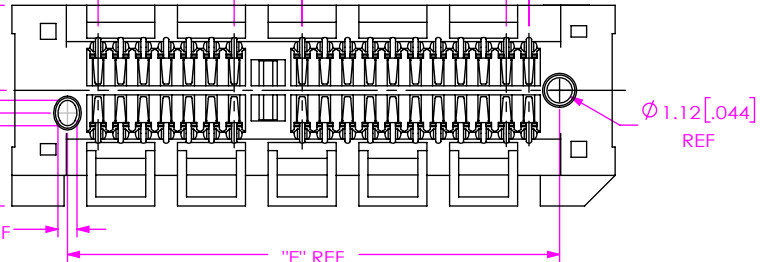
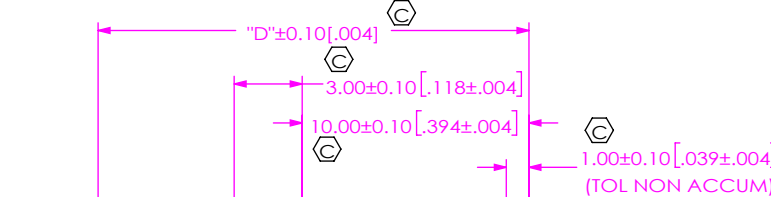
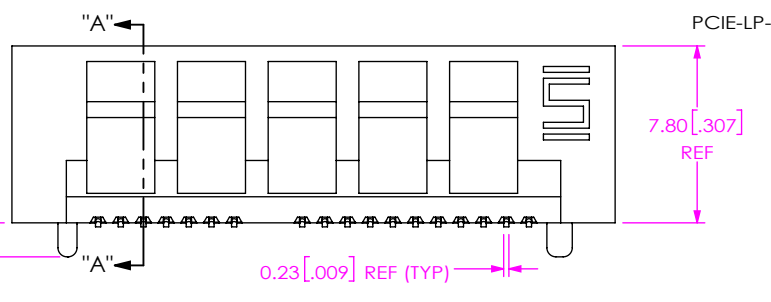
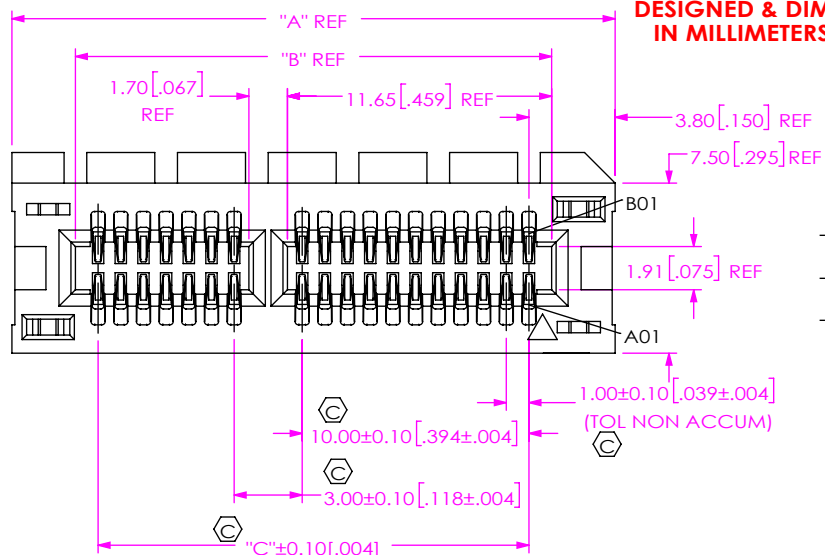
CARD THICKNESS
-01: 1.57mm (.062) CARD

PLATING SPECIFICATION
-F: 3µ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL
-S: 30µ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL
-L: 10µ" LIGHT SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL

PACKAGING
BLANK: TRAY (FOR 16 LANES ONLY)
-TR: TAPE & REEL (SEE NOTES 7 & 8)
-FR: FULL REEL QTY TAPE & REEL (SEE NOTES 7 & 8)
(-XR PACKAGING AVAILABLE FOR -01, -04 & -08 LANES ONLY)

PICK & PLACE OPTION
-K: POLYIMIDE FILM PAD (SEE FIG 3, SHT 2)

OPTION
-WT: WELD TAB (SEE FIG 2, SHT 2)



- NOTES:
- ⊕ REPRESENTS A CRITICAL DIMENSION. PCIE-LP-01-01-X-DV-A-XX SHOWN
 - DIMENSIONS MEASURED TIP TO TIP.
 - MINIMUM PUSHOUT FORCE: SIGNAL: 2.2N, WELD TAB: 4.45N.
 - MATING CARD MUST HAVE LEAD-IN. SEE SAMTEC FOOTPRINT FOR SPECIFICATIONS.
 - NOTE DELETED.
 - NOTE DELETED.
 - ORDERS WILL BE PACKAGED ACCORDING TO THE SAMTEC PACKAGING EFFICIENCY STANDARDS (SPES) FOUND ON WWW.SAMTEC.COM.
 - ATTACH LABEL TO EACH REEL.

FIG 1

ALIGNMENT PIN

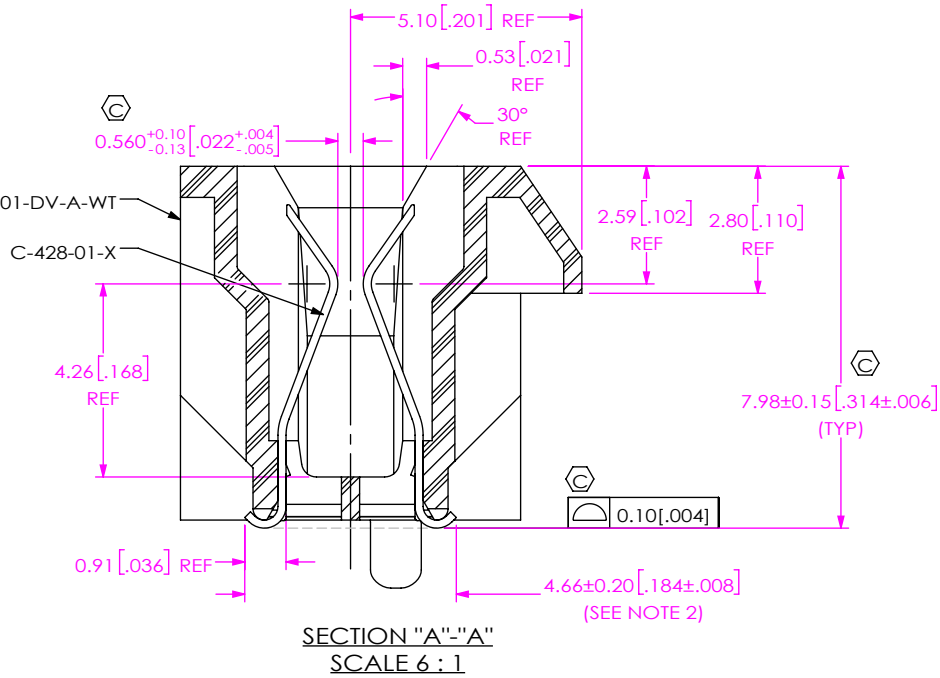


TABLE 1

No OF LANES	"A"	"B"	"C"	"D"	"E"
-01	26.60 [1.047]	21.00 [0.827]	19.00 [0.748]	19.00 [0.748]	21.70 [0.854]
-04	40.60 [1.598]	35.00 [1.378]	33.00 [1.299]	33.00 [1.299]	35.70 [1.406]
-08	57.60 [2.268]	52.00 [2.047]	50.00 [1.969]	50.00 [1.969]	52.70 [2.075]
-16	90.60 [3.567]	85.00 [3.346]	83.00 [3.268]	83.00 [3.268]	85.70 [3.374]

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS. TOLERANCES ARE:
DECIMALS ANGLES
X.X: ±0.3 [0.1] 2°
X.XX: ±0.13 [0.005]
X.XXX: ±0.051 [0.0020]

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520 PARK EAST BLVD. NEW ALBANY, IN 47150
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MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 3:1
INSULATOR: LCP, UL 94 V0, COLOR: BLACK
CONTACT: PHOS BRONZE
WELD TAB: BRASS ALLOY

DESCRIPTION:
PCI EXPRESS LOW PROFILE ASSEMBLY
DWG. NO.
PCIE-LP-XX-01-X-DV-A-XX-X-XX

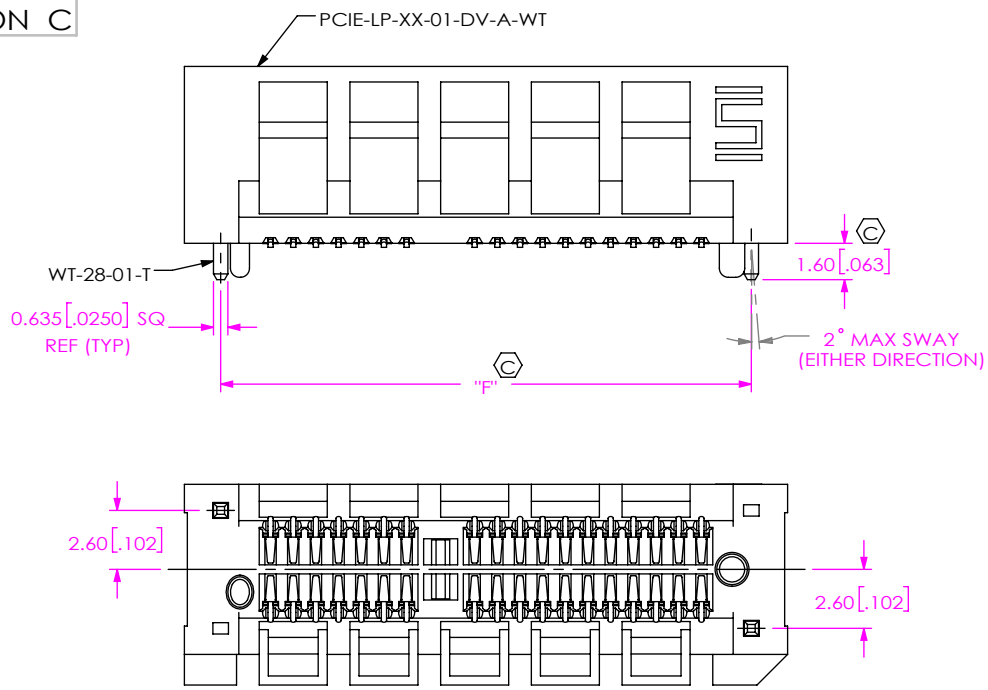
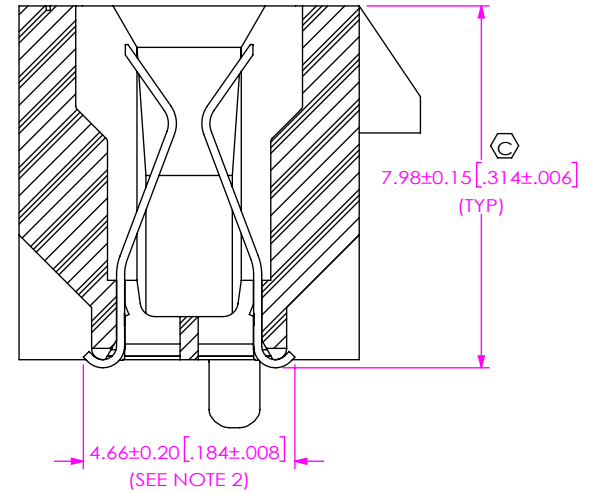


FIG 2
 PCIE-LP-01-01-X-DV-A-WT-XX SHOWN
 (DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)

TABLE 2		
No OF LANES	"F"	"G"
-01	23.40 [.921]	8.80 [.346]
-04	37.40 [1.472]	15.80 [.622]
-08	54.40 [2.142]	24.30 [.957]
-16	87.40 [3.441]	40.80 [1.606]



IN-PROCESS 1
 (FILL C-428-01-X)

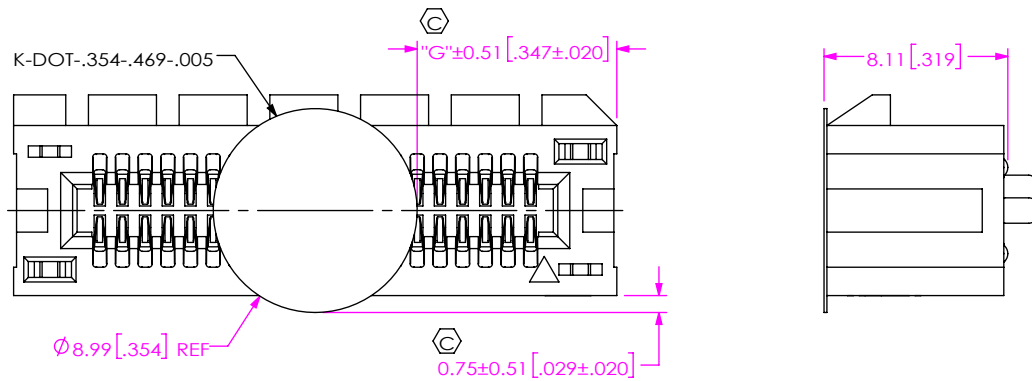


FIG 3
 PCIE-LP-01-01-X-DV-A-K-XX SHOWN
 (DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)

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DO NOT SCALE DRAWING

SHEET SCALE: 3:1

DESCRIPTION:
 PCI EXPRESS LOW PROFILE ASSEMBLY

DWG. NO.
PCIE-LP-XX-01-X-DV-A-XX-X-XX

BY: JESSIE W 6/30/2016 SHEET 2 OF 2